

Amphenol	The Product Specification for Slim Cool Edge, 0.65mm pitch, Vertical Connector, Gen6	Product Spec. # SSE022		Date: 2024/12/05
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**The Product Specification for
Slim Cool Edge, 0.65mm pitch, Vertical Connector, Gen6
(Signal only and Hybrid with 100A Power Block)**

REVISION RECORD

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Prepared by : Nick.yang	Date: 2024/12/05	Approved by : Brade.zou	Date: 2024/12/05
(Product Engineer)		(Engineering Manager)	

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1. OBJECTIVE

This specification defines the performance, test, quality and reliability requirements of Amphenol 0.65pitch Slim Cool Edge vertical connector, signal only and hybrid with 100A power block.

2. SCOPE

This Specification includes the Materials/Finishing, Mechanical Characteristics, Electrical Characteristics and Environmental requirements of Amphenol 0.65pitch Slim Cool Edge vertical connector, signal only and hybrid with 100A power block.

3. APPLICABLE DOCUMENTS

3.1. Application

3.1.1. Engineering drawings

3.2. Military Standards

3.2.1. MIL-C-45662: Equipment Calibration

3.3. Other Standards and Specifications

3.4.1. UL94 V-0 : Tests for Flammability of Plastic Materials in Devices and Appliances

3.4.2. EIA 364 : Electrical Connector/Socket Test Procedures Including Environmental Classifications

3.4.3. EIA 364 -1000: Environmental test methodology for assessing the performance of electrical connectors and sockets used in business office applications.

4. REQUIREMENTS

4.1. Qualification

Connectors furnished under this specification shall be capable of meeting the qualification test requirements specified herein. Unless otherwise specified, all measurements shall be performed within the following lab conditions:

- a) Temperature: 25°C ±10°C.
- b) Relative Humidity: 20% to 80%
- c) Atmospheric Pressure: 650mm to 800mm of Hg (86 ~106Kpa)

4.2. Material

Material for each part shall be specified herein, or equivalent. Substitute material shall meet the performance requirements of this specification.

- a) Contacts: Copper and Copper alloy.
- b) Power block: Copper and Copper alloy.
- c) Insulator: High temperature Engineering plastics, UL94 V-0.
- d) Other material: Stainless steel

4.3. Finish

Plated finished for qualification components shall be meet the connector's application.

4.4. Workmanship

Connectors shall be uniform in quality and shall be free from burrs, scratches, cracks, voids, chips, blisters, pin holes, sharp edges, and other defects that will adversely affect product's life or serviceability.

5. RATINGS

- 5.1. Operating temperature: -55°C to +105°C.
5.2. Storage conditions: -5°C to +30°C and 20%RH to 75% RH;

6. ELECTRICAL CHARACTERISTIC

6.1. Current Rating

The temperature rise above ambient shall not exceed 30°C at any point in the system when contact positions specified are powered at the power levels specified herein:

- Ambient Conditions: still air at 25°C ±5°C.
- Current Rating for power block is 100A/EA.
- Current Rating for signal pin, please refer to table 1.
- Reference: EIA 364-70.
- Mated with applicable PCB and power guide pin.

Table 1

PIN COUNT	CURRENT (A)
≤ 10pin	1.0
≤ 20pin	0.8
≤ 60pin	0.6
> 60pin	0.5

6.2. Low Level Contact Resistance (Signal contact)

Mated with applicable board, the low-level contact resistance shall not exceed a change of 20mΩ for signal Pin (The maximum initial contact resistance is 45mΩ) after environmental exposure and durability, when measured in accordance with EIA 364-23. The following details shall apply:

- Test Voltage: 20mV DC maximum at open circuit.
- Test Current: not to exceed 100mA.

6.3. Contact Resistance (Power block)

Mated with applicable power pin, the contact resistance shall not exceed 1.0mΩ for Power pin before and after environmental exposure and durability, when measured in accordance with EIA 364-06. The following details shall apply:

- Current Rating for power pin is 100A/EA.
- Mated with applicable power guide pin.

6.4. Insulation Resistance

The insulation resistance shall not be less than 1000MΩ between adjacent power Pin and 1000MΩ between adjacent signal Pin when measured in accordance with EIA 364-21. The following details shall apply:

- Test Voltage: 500V DC.
- Preparation: The connectors shall be Unmated.
- Electrification Time: 1 minute.
- Point of Measurement: Between adjacent contacts.

6.5. Dielectric Withstanding Voltage

There shall be no evidence of arc-over, insulation breakdown, or excessive leakage current (0.5mA max) when tested in accordance with EIA 364-20. The following details shall apply:

- a) Test Voltage: 1500V DC for power pin and 500V DC for signal pin
- b) Test Duration: 1 minute
- c) Test Conditions: EIA 364-20 Test Conditions I (685~785mm of mercury, and sea level)
Points of measurement: Between adjacent contacts (method B).

7. MECHANICAL CHARACTERISTIC

7.1. Durability

Mating and un-mating with applicable PCB, Durability tested in accordance with EIA-364-09.

The following details shall apply:

- a) Number of Cycles: 200 cycles.
- b) Cycling Rates: 500±50 cycles/hour.
- c) No physical damage.

7.2. Durability(Preconditioning)

Mating and un-mating with applicable PCB, Durability tested in accordance with EIA-364-09.

The following details shall apply:

- a) Number of Cycles: 20 cycles.
- b) Cycling Rates: 500±50 cycles/hour.
- c) No physical damage.

7.3. Mating/un-mating Force

Mating with the applicable PCB, the following details shall apply:

- a) Reference: EIA 364-13.
- b) Speed Rate: 25.4±3mm/minute.
- c) Mating force: 0.6N /pin max for signal pin and 30N/pin max for power block.

Un-mating force: 0.04N /pin min for signal pin and 4N /pin min for power block.

Note:

For a connector with specific pin count and configuration, the total force data can be calculated, as below.

Connector pin count and configuration	Mating Force ¹⁾	Un-mating Force	Remark
226 signal pin	135.6N Max.	9.04N Min.	
250 signal pin	150.0N Max.	10.0N Min.	
226 signal pin and 1 power block	165.6N Max.	13.04N Min.	
250 signal pin and 1 power block	180.0N Max.	14.0N Min.	
226 signal pin and 2 power block	195.6N Max	17.04N Min	
250 signal pin and 2 power block	210.0N Max	18.0N Min	

- 1) The estimated mating force listed in this table is based on extreme situation, that connector is mated with the thickest PCB.
Generally, the actual force will be about 75% of these extreme force if mated with nominal thickness PCB.

7.4. Contact Retention Force

The contact and the insulator are axially pull out at the speed rate of 25.4±3mm/minute

- a) Reference: EIA 364-29.
- b) Contact Retention force for power block: 3N/pin Min.
- c) Contact Retention force signal pin: 1.5N/pin Min.

7.5. Reseating

- a) Test condition: Manually mating and un-mating the connector with applicable PCB.
- b) Requirement: Perform 3 such cycles.

8. ENVIRONMENTAL CHARACTERISTIC**8.1. Thermal Shock.**

Mated with applicable card and power guide pin. No physical damage shall be observed after tested in accordance with EIA 364-32. The following details shall apply:

- a) Reference: EIA 364-32, method A,
- b) Test condition: test condition I
 - step 1: -55 °C, 30minutes min
 - step 2: 25 °C, 5minutes max
 - step 3: 85 °C, 30minutes min
 - step 4: 25 °C, 5minutes max
- c) Number of cycles: test duration A-4 (10 continuous cycles).

8.2. Humidity- Temperature Cycling

Mated with applicable card and power guide pin. No physical damage shall be observed after tested in accordance with EIA 364-31, method VIII. The following details shall apply:

- a) Temperature: 25 °C ±3 °C to 65 °C ±3 °C;
- b) Humidity: 50 % RH ±5 % to 80 % RH ±5 %
- c) See figure 5 for temperature and humidity profile;
- d) Cycle duration: 3 hours;
- e) Duration: 24 cycles.

8.3. Thermal Cycling

Mated with applicable card and power guide pin. No physical damages shall be observed after tested in accordance with EIA-364-110,

- a) Test condition: Cycle the connector between 15 °C ±3 °C and 85 °C ±3 °C, Humidity is not controlled
- b) Test Duration: Ramps should be a minimum of 2 °C per minute, and dwell times should insure that the contacts reach the temperature extremes (a minimum of 5 minutes)
- c) Number of cycles: Perform 500 such cycles.

8.4. Thermal Disturbance

Mated with applicable card and power guide pin. No physical damages shall be observed after tested in accordance with EIA-364-110,

- a) Test condition: Cycle the connector between $15\text{ }^{\circ}\text{C} \pm 3\text{ }^{\circ}\text{C}$ and $85\text{ }^{\circ}\text{C} \pm 3\text{ }^{\circ}\text{C}$, Humidity is not controlled
- b) Test Duration: Ramps should be a minimum of $2\text{ }^{\circ}\text{C}$ per minute, and dwell times should insure that the contacts reach the temperature extremes (a minimum of 5 minutes)
- c) Number of cycles: Perform 10 such cycles

8.5. Dust Contamination

Perform in accordance with EIA 364-91 Dust contamination 1 (benign), unmated receptacle connectors.

8.6. Temperature Life.

Mated with applicable card and power guide pin. No physical damage shall be observed after tested in accordance with EIA-364-17. The following details shall apply:

- a) Test Duration: 240 hours.
- b) Temperature: $105\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$.

8.7. Temperature Life (Preconditioning).

Mated with applicable card and power guide pin. No physical damage shall be observed after tested in accordance with EIA-364-17. The following details shall apply:

- a) Test Duration: 120 hours.
- b) Temperature: $105\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$.

8.8. Physical Shock

Mated with applicable card and power guide pin. No discontinuities greater than $1\text{ }\mu\text{s}$ and no physical damage shall be observed after tested in accordance with EIA 364-27. The following details shall apply:

- a) Test condition: A (490 m/s^2 , 11 ms, half-sine).
- b) 3 shocks in both directions along each of three orthogonal axes (18 totals).
- c) Mounting: Rigidly mount assemblies.
- d) Apply current: 10mA.

8.9. Vibration

Mated with applicable card and power guide pin. No discontinuities greater than $1\text{ }\mu\text{s}$ and no physical damage shall be observed after tested in accordance with EIA 364-28 The following details shall apply:

- a) Test condition: EIA 364-28, Test condition VII, test condition letter D
- b) Test Duration: 15 minutes in each of 3 mutually perpendicular directions
- c) Mounting: Rigidly fixed assemblies.

8.10. Salt Spray

Mated with applicable card and power guide pin. No abnormal nicks, cracks, or scratches on finished surfaces that indicate the removal of the normal protective coating. The following details shall apply:

- a) Reference: EIA 364-26, Test Condition B.
- b) Temperature: $35\text{ }^{\circ}\text{C} +1/-2\text{ }^{\circ}\text{C}$.
- c) Humidity: 95%~98% RH.
- d) Concentration: 5%;
- e) Duration: 48 hours.

8.11. Solder ability

The termination is at least 95% covered by a contact in accordance with EIA 364-52. The following details shall apply:

- a) Solder Time: 2~3seconds.
- b) Solder Temperature: 245°C ± 5°C.

8.12. Porosity Testing

Tested in accordance with EIA 364-53, minimum of 10 contacts from 3 samples must be tested, optical microscope of 10X magnification concentrated reagent grade nitric acid: 75%+/-1% HNO3.

8.13. Mix Flowing Gas (MFG)

The following details shall apply:

- a) Reference: EIA 364-65, Class IIA
- b) Gas Concentration: Cl2 10±3ppb, NO2 200±50ppb, H2S 10±5ppb, SO2 100±20ppb
- c) Temperature: 30±1 °C;
- d) Humidity: 70±2% RH
- e) Test Duration: exposed 160hours un-mating with applicable PCB and 80 hours mating with applicable PCB

8.14. Resistance to Soldering Heat.

No physical damage shall be observed after tested, the following details shall apply:

- a) Reference: EIA 364-56, procedure 6
- b) Test Temperature: test level 3(250°C+10°C/-0°C)

9. QUALITY ASSURANCE PROVISIONS

9.1. Equipment Calibration

All test equipment and inspection facilities used in the performance of any test shall be maintained in a calibration system in accordance with MIL-C-45662 and ISO 9000.

9.2. Inspection Condition

Unless otherwise specified herein, all inspections shall be performed under the following ambient conditions:

- a) Temperature: 25°C ±10°C.
- b) Relative Humidity: 20% to 80%
- c) Atmospheric Pressure: 650mm to 800mm of Hg (86 ~106Kpa)

9.3. Sample Quantity and Description

The sample size to be tested in each group shown in Qualification Testing Sequences should follow **Table 2**, All samples must be free of defects that would impair normal connector operation. All samples must meet dimensional requirements of connector.

9.4. Acceptance

- 9.4.1. Electrical and mechanical requirements placed on test samples as indicated in Paragraphs 5 and Paragraphs 6 shall be established from test data using appropriate statistical techniques or shall otherwise be customer specified, and all samples tested in accordance with this product specification shall meet the stated requirements.
- 9.4.2. Failures attributed to equipment, test set up, or operator error shall not disqualify the product. If product failure occurs, corrective actions shall not disqualify the product. If product failure occurs, corrective action shall be taken and samples resubmitted for qualification.

9.5. Qualification Testing

Qualification testing shall be performed on sample units produced with equipment and procedures normally used in production. The test sequence shall be as shown in Qualification Testing Sequences
Visual Examination: EIA 364-18

9.6. Re-qualification Testing

If any of the following conditions occur, the responsible product engineer shall initiate re-qualification testing consisting of all applicable parts of the qualification test matrix Table 1.

- a) A significant design change is made to the existing product which impacts the product form, fit or function. Examples of significant changes shall include, but not be limited to, changes in the plating material composition or thickness, contact force, contact surface geometry, insulator design, contact base material, or contact lubrication requirements.
- b) A significant change is made to the manufacturing process, which impacts the product form, fit or function.
- c) A significant event occurs during production or end use requiring corrective action to be taken relative to the product design or manufacturing process.

Table 2: Qualification Testing Sequences

TEST OR EXAMINATION	TEST GROUP														
	item	A	B	C	D	E	F	G	H	I	J	K	L	M	N
Examination of connector(s)	4.4	1,11	1,14	1,14	1,12	1,14	1,14	1,11	1	1	1	1	1	1	1
Current Rating	6.1								2						
LLCR(signal)	6.2	2,6,9	2,6 9,12	2,6 9,12	2,5,7 9,11	2,6 9,12	2,6 9,12	4,7							
Contact Resistance(power)	6.3	3,7,10	3,7 10,13	3,7 10,13		3,7 10,13	3,7 10,13	5,8							
Insulation Resistance	6.4							3,10							
Dielectric Withstanding Voltage	6.5							2,9							
Durability	7.1							6							
Durability (Preconditioning)	7.2	4	4	4	3	4	4								
Matting/un-mating Force	7.3									3,6					
Contact Retention Force	7.4										2				
Reseating	7.5	8	11		10	11	11			2,5					
Thermal Shock	8.1		5												
Humidity-Temperature Cycling	8.2		8												
Thermal Cycling	8.3					8									
Mixed flowing gas	8.12				6										
Thermal disturbance	8.4				8		8								
Dust contamination	8.5						5								
High Temperature Life	8.6	5								4					
High Temperature Life (Preconditioning)	8.7			5	4	5									
Physical Shock	8.8			11											
Vibration	8.9			8											
Salt Spray	8.10										2				
Porosity Testing	8.11											2			
Solder ability	8.13												2		
Resistance to Soldering Heat	8.14													2	
Sample size		10	10	10	10	10	10	10	5	5	5	5	5	5	5